

## Material Set Change:

Package Material Set		Carsem	ASE Chungli
MSOP	Die Attach	Ablestik 84-1 LMISR4	Hitachi EN4900
	Mold Compound	Sumitomo 6600H	Sumitomo G700
	Wire	0.8mil, 1.0mil and 1.2/1.3 mil Gold wire	0.8mil, 1mil and 1.2/1.3mil Gold Wire

***Qualification of ASE Chungli, as an Alternate Assembly Site for MSOP Packages***

**Qualification Results Summary of MSOP Package  
at ASE Chungli**

Test	QUALIFICATION RESULT		
	Specification	Sample Size	Results
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	<b>Pass</b>
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	<b>Pass</b>
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	<b>Pass</b>
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	<b>Pass</b>

\*Preconditioned per JEDEC/IPC J-STD-020